

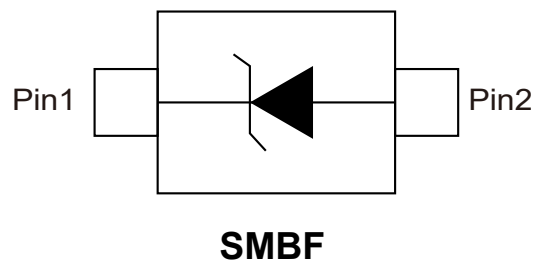
1.Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

2.Mechanical Data

- Case: JEDEC SMBF molded plastic body
- Mounting Position: Any
- Weight:57mg/0.002oz
- Terminals: leads solderable per MIL-STD-750 Method 2026

3.Pinning information





4. Maximum Ratings And Electrical Characteristics

Parameter		Symbol	SS 32BF	SS 34BF	SS 36BF	SS 38BF	SS 310BF	SS 315BF	SS 320BF	Units
Maximum Repetitive Peak Reverse Voltage		V _{RRM}	20	40	60	80	100	150	200	V
Maximum RMS Voltage		V _{RMS}	14	28	42	56	70	105	140	V
Maximum DC Blocking Voltage		V _{DC}	20	40	60	80	100	150	200	V
Maximum average forward rectified current at T _L (see fig.1)		I _(AV)	3							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)		I _{FSM}	80			70				A
Maximum instantaneous forward voltage at 3A		V _F	0.55		0.7	0.85		0.95		V
Maximum DC Reverse Current at Rated DC Reverse Voltage	T _A =25°C	I _R	0.5			0.3				mA
	T _A =100°C		5			3				mA
Typical Junction Capacitance (Note1)		C _J	450			400				pF
Typical Thermal Resistance (Note 2)		R _{θJA}	50							°C/W
Junction Temperature Range		T _J	-50 to 125							°C
Storage Temperature Range		T _{STG}	-50 to 150							°C

Ratings at 25 C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Notes:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas.



5. Typical characteristic

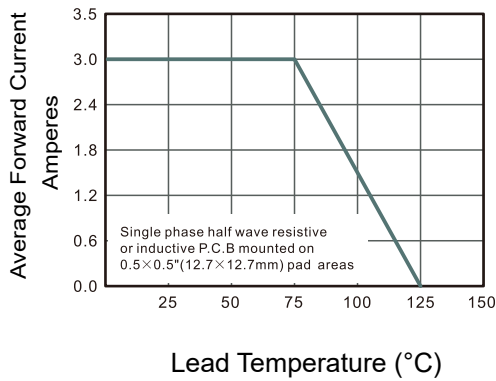


Figure 1: Forward Current Derating Curve

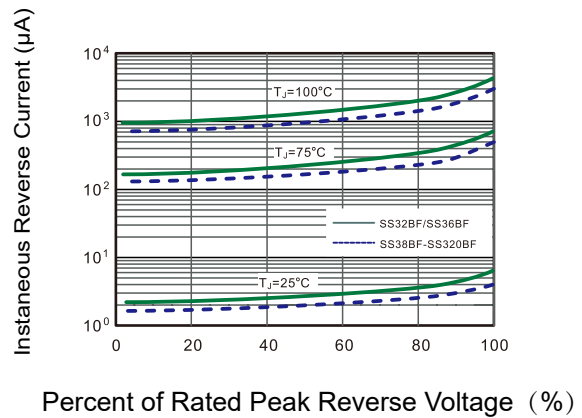


Figure 2: Typical Reverse Characteristics

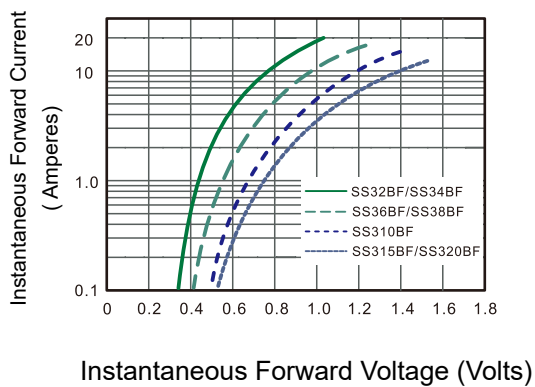


Figure 3: Typical Forward Characteristic

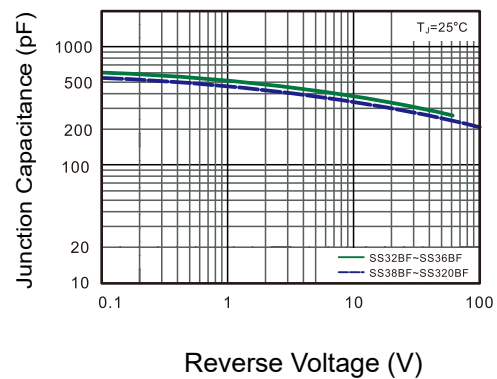


Figure 4: Typical Junction Capacitance

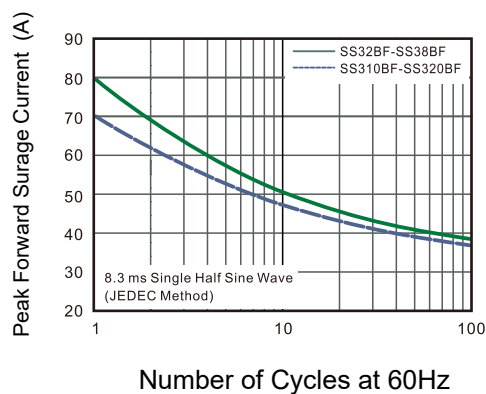


Figure 5: Maximum Non-Repetitive Peak Forward Surge Current

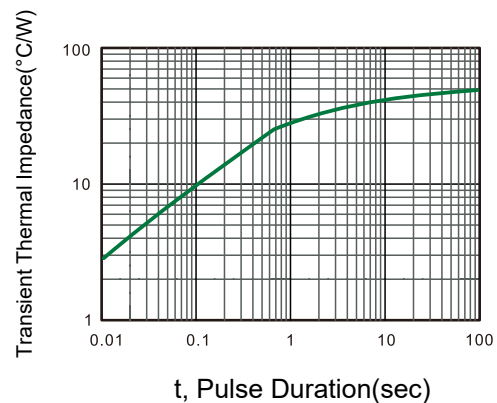
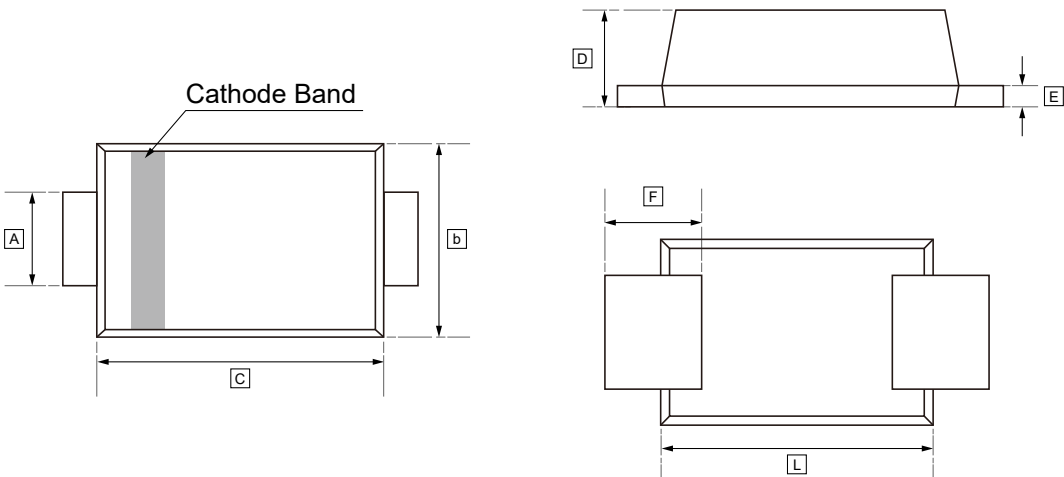


Figure 6: Typical Transient Thermal Impedance



6.SMBF Package Outline Dimensions

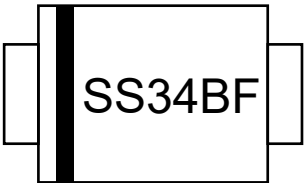


DIMENSIONS (mm are the original dimensions)

Symbol	A	b	C	D	E	F	L
Min	1.90	3.50	4.2	1.10	0.18	1.0	5.10
Max	2.20	3.70	4.4	1.30	0.26	1.30	5.5



7 .Ordering information



Order Code	Marking	Package	Base QTY	Delivery Mode
UMW SS32BF	SS32BF	SMBF	3000	Tape and reel
UMW SS34BF	SS34BF	SMBF	3000	Tape and reel
UMW SS36BF	SS36BF	SMBF	3000	Tape and reel
UMW SS38BF	SS38BF	SMBF	3000	Tape and reel
UMW SS310BF	SS310BF	SMBF	3000	Tape and reel
UMW SS315BF	SS315BF	SMBF	3000	Tape and reel
UMW SS320BF	SS320BF	SMBF	3000	Tape and reel



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